

applying said application liquid to a pixel column by ultrasonic oscillations.

7. A method of manufacturing a self-light-emitting device according to claim 6, wherein:  
said nozzle has a large internal diameter portion and a small internal diameter portion;  
said small internal diameter portion has a heater; and  
said heater applies heat to the application liquid filling the nozzle.

10. (Twice Amended) A method of manufacturing a self-light-emitting device according to  
claim 6, wherein said application liquid is pushed out from said nozzle by pressurization, and is  
applied.

b2  
11. (Twice Amended) A method of manufacturing a self-light-emitting device according to  
claim 6, wherein said application liquid is pushed out from said nozzle by a medium selected from  
a group consisting of capillary action, the weight of said application liquid, and pressure, and is  
applied.

12. (Twice Amended) A method of manufacturing a self-light-emitting device according to  
claim 19, wherein said application liquid filling said nozzle is applied by contacting a contact  
element of said nozzle with said bank.

Please add the following new claims:

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19. (New) A method of manufacturing a light-emitting device according to claim 6, wherein  
said self-light-emitting device comprises a pixel electrode over a substrate and a bank covering at

least an edge portion of said pixel electrode over said substrate.

20. (New) A method of manufacturing a light-emitting device comprising:  
filling a nozzle with an application liquid for forming an EL layer; and  
applying said application liquid to a pixel column by ultrasonic oscillations and heat.

21. (New) A method of manufacturing a light-emitting device according to claim 20, wherein  
said nozzle has a large internal diameter portion and a small internal diameter portion, said small  
internal diameter portion has a heater, and said heater applies heat to the application liquid filling  
the nozzle.

22. (New) A method of manufacturing a light-emitting device according to claim 20, wherein  
said application liquid is pushed out from said nozzle by pressurization, and is applied.

23. (New) A method of manufacturing a light-emitting device according to claim 20, wherein  
said application liquid is pushed out from said nozzle by a medium selected from a group consisting  
of capillary action, the weight of said application liquid, and pressure, and is applied.

24. (New) A method of manufacturing a light-emitting device according to claim 20, wherein  
said light-emitting device comprises a pixel electrode over a substrate and a bank covering at least  
an edge portion of said pixel electrode over said substrate.

25. (New) A method of manufacturing a light-emitting device according to claim 24, wherein

said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.

26. (New) A method of manufacturing a light-emitting device comprising:  
forming a thin film transistor over a substrate;  
forming an insulating film over said thin film transistor;  
forming a pixel electrode over said insulating film;  
forming a bank covering at least an edge portion of said pixel electrode over said insulating film;

filling a nozzle with an application liquid for forming an EL layer; and  
applying said application liquid to a pixel column by ultrasonic oscillations.

27. (New) A method of manufacturing a light-emitting device according to claim 26, wherein  
said nozzle has a large internal diameter portion and a small internal diameter portion, said small  
internal diameter portion has a heater, and said heater applies heat to the application liquid filling  
the nozzle.

28. (New) A method of manufacturing a light-emitting device according to claim 26, wherein  
said application liquid is pushed out from said nozzle by pressurization, and is applied.

29. (New) A method of manufacturing a light-emitting device according to claim 26, wherein

said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, the weight of said application liquid, and pressure, and is applied.

30. (New) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.

#### REMARKS

Applicants will address each of the Examiner's objections and rejections in the order in which they appear in the Office Action.

#### Election/Restriction

In response to the initial restriction requirement, Applicants elected Group II, Claims 6-7 and (10-12)/6 which was described as being "drawn to a method of depositing an electroluminescent layer of an EL device". Applicants also added new method Claims 13-18.

In the 9-25-02 Office Action, the Examiner alleges that new Claims 13-18 are directed to an independent invention and that the elected invention has "a separate utility such as applying the liquid with heat and without ultrasound oscillations or electric voltage."

Applicants do not understand the Examiner's restriction and request reconsideration thereof. This is especially true in light of the amendment herein to Claim 6 to eliminate the phrase "or heat."

Applicants are also adding herewith new Claims 19-30. It is believed that these claims also fall within the elected invention as they are directed to a method, and independent Claim 20 recites